

B. Amendment to the Specification

Please amend the paragraph at page 2, lines 13-23, as follows.

In the conventional wet processing method, a processing solution such as a chemical solution or pure water sometimes does not reliably enter deep in a depression due ~~owing~~ to the interference caused by the surface tension (contact angle) determined by the type of the processing solution and the contact surface (material)[[,]] or the interface by an air bubble in the depression. The smaller the size of a trench, the less easily a liquid is supplied deep in a depression (“Silicon Wafer Surface Cleaning Technique New Edition” edited and written by Takeshi Tsyuoshi Hattori, 2001, issued by Realize Inc., page 454, right ~~left~~ column, lines 1 to 16 ~~17~~).